ABSTRACT

PACKAGING USING FLEXIBLE FOLDING INTERPOSER SUBSTRATE

Semiconductor device assemblies incorporating multiple semiconductor dice using a flexible, folded interposer substrate. The semiconductor device assembly includes a conductively bumped semiconductor die and an interposer substrate having multiple recesses formed therein. All of the semiconductor dice are mounted to the same side of the interposer substrate with the conductive bumps disposed in the multiple recesses so that the active surface of the semiconductor die is directly mounted to a facing surface of the interposer substrate. The interposer substrate is folded so that all of the semiconductor dice are in substantial superimposition.

[FIG. 19]